



Material Content Data Sheet



Sales Product Name				IPI80N08S4-06		Issued		24. January 2018	
MA#				MA001658126					
Package				PG-TO262-3-1		Weight*		1573.25 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	4.425	0.28	0.28	2813	2813	
leadframe	inorganic material	phosphorus	7723-14-0	0.255	0.02		162		
	non noble metal	iron	7439-89-6	0.851	0.05		541		
	non noble metal	copper	7440-50-8	849.682	54.01	54.08	540082	540785	
	non noble metal	aluminium	7429-90-5	5.810	0.37	0.37	3693	3693	
wire	non noble metal	aluminium	7429-90-5	5.810	0.37	0.37	3693	3693	
encapsulation	organic material	carbon black	1333-86-4	8.805	0.56		5597		
	plastics	epoxy resin	-	96.853	6.16		61562		
	inorganic material	silicondioxide	60676-86-0	481.329	30.59	37.31	305946	373105	
leadfinish	non noble metal	tin	7440-31-5	15.198	0.97	0.97	9660	9660	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1		
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	145	146	
solder	non noble metal	tin	7440-31-5	0.069	0.00		44		
	noble metal	silver	7440-22-4	0.087	0.01		55		
	non noble metal	lead	7439-92-1	3.305	0.21	0.22	2101	2200	
heatspreader	inorganic material	phosphorus	7723-14-0	0.032	0.00		20		
	non noble metal	iron	7439-89-6	0.106	0.01		68		
	non noble metal	copper	7440-50-8	106.210	6.75	6.76	67510	67598	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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